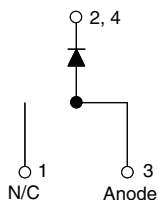


HEXFRED®, Ultrafast Soft Recovery Diode, 4 A



TO-252AA (D-PAK)



FEATURES

- Ultrafast recovery time
- Ultrasoft recovery
- Very low I_{RRM}
- Very low Q_{rr}
- Guaranteed avalanche
- Specified at operating temperature
- AEC-Q101 qualified
- Meets JESD 201 class 2 whisker test
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

PRODUCT SUMMARY

Package	TO-252AA (D-PAK)
$I_{F(AV)}$	4 A
V_R	600 V
V_F at I_F	1.4 V
t_{rr} typ.	17 ns
T_J max.	150 °C
Diode variation	Single die

BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION / APPLICATIONS

These diodes are optimized to reduce losses and EMI / RFI in high frequency power conditioning systems. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for freewheeling, flyback, power converters, motor drives, and other applications where high speed and reduced switching losses are design requirements.

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	V_{RRM}		600	V
Maximum continuous forward current	$I_{F(AV)}$	$T_C = 100\text{ °C}$	4	A
Single pulse forward current	I_{FSM}		25	
Repetitive peak forward current	I_{FRM}	$T_C = 116\text{ °C}$	16	
Maximum power dissipation	P_D	$T_C = 100\text{ °C}$	10	W
Operating junction and storage temperatures	T_J, T_{Stg}		-55 to +150	°C

**ELECTRICAL SPECIFICATIONS** ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Forward voltage See fig. 1	V_F	$I_F = 4\text{ A}$	-	1.5	1.8	
		$I_F = 8\text{ A}$	-	1.8	2.2	
		$I_F = 4\text{ A}, T_J = 125\text{ }^{\circ}\text{C}$	-	1.4	1.7	
Maximum reverse leakage current	I_R	$V_R = V_R\text{ rated}$	-	0.17	3.0	μA
		$T_J = 125\text{ }^{\circ}\text{C}, V_R = 0.8 \times V_R\text{ rated}$	-	44	300	
Junction capacitance	C_T	$V_R = 200\text{ V}$	-	4	8	pF
Series inductance	L_S	Measured lead to lead 5 mm from package body	-	8.0	-	nH

DYNAMIC RECOVERY CHARACTERISTICS ($T_C = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	$I_F = 1.0\text{ A}, dI_F/dt = 200\text{ A}/\mu\text{A}, V_R = 30\text{ V}$	-	17	-	ns
		$T_J = 25\text{ }^{\circ}\text{C}$	-	28	42	
		$T_J = 125\text{ }^{\circ}\text{C}$	-	38	57	
Peak recovery current	I_{RRM}	$T_J = 25\text{ }^{\circ}\text{C}$	-	2.9	5.2	A
		$T_J = 125\text{ }^{\circ}\text{C}$	-	3.7	6.7	
Reverse recovery charge	Q_{rr}	$T_J = 25\text{ }^{\circ}\text{C}$	-	40	60	nC
		$T_J = 125\text{ }^{\circ}\text{C}$	-	70	105	
Rate of fall of recovery current	$dI_{(rec)M}/dt$	$T_J = 25\text{ }^{\circ}\text{C}$	-	280	-	A/ μs
		$T_J = 125\text{ }^{\circ}\text{C}$	-	235	-	

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-55	-	150	$^{\circ}\text{C}$
Thermal resistance, junction to case	R_{thJC}		-	-	5.0	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction to ambient	R_{thJA}	Typical socket mount	-	-	80	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-252AA (D-PAK)	HFA04SD60SH			

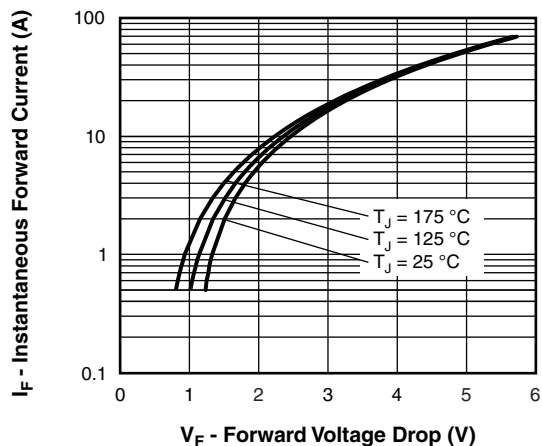


Fig. 1 - Typical Forward Voltage Drop Characteristics

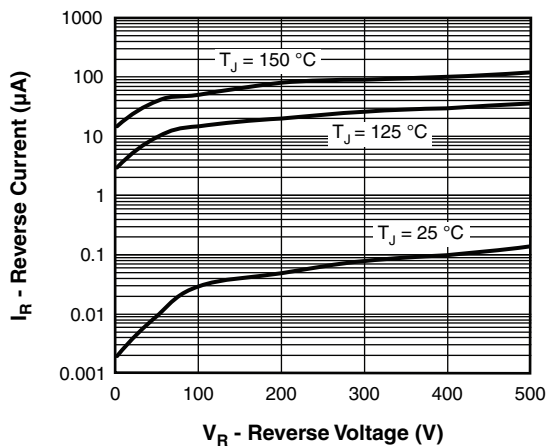


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

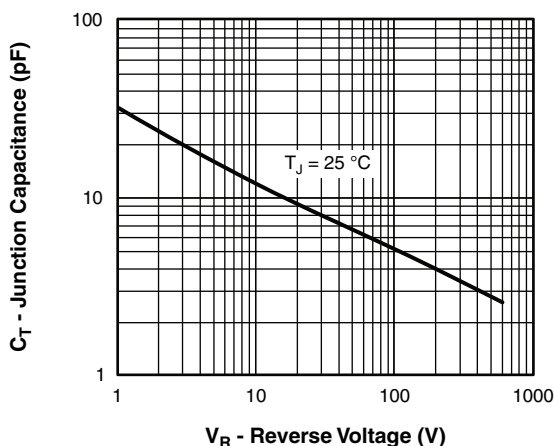
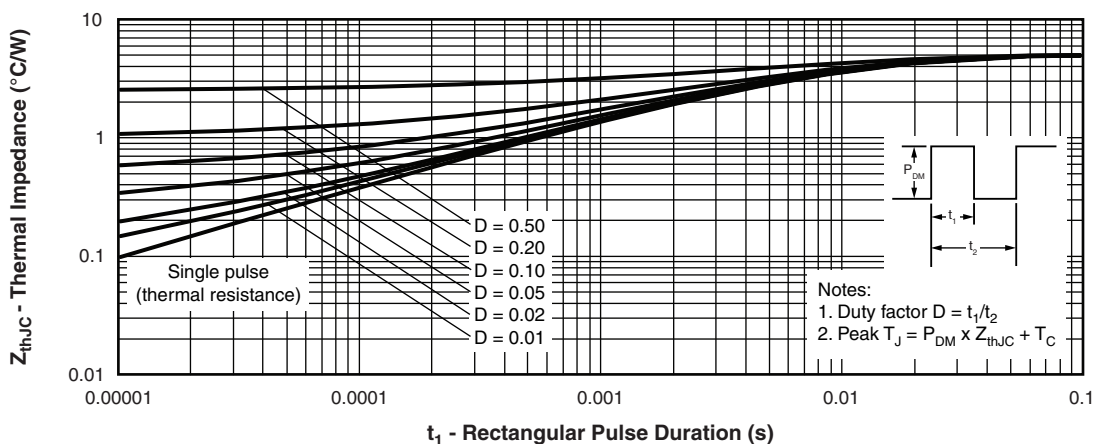
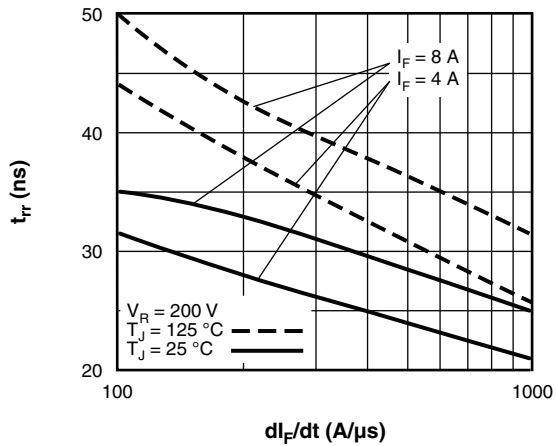
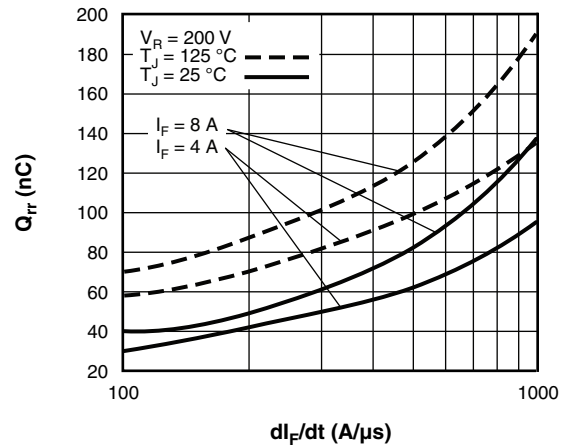
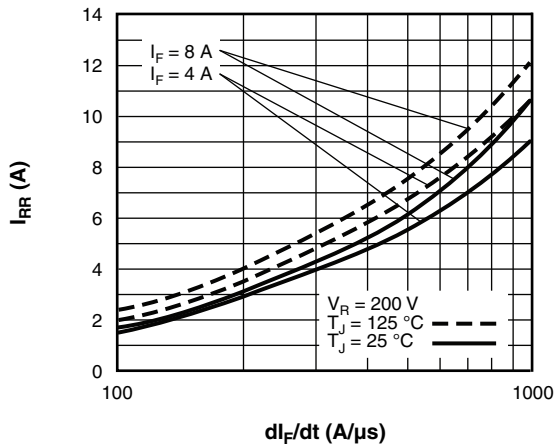
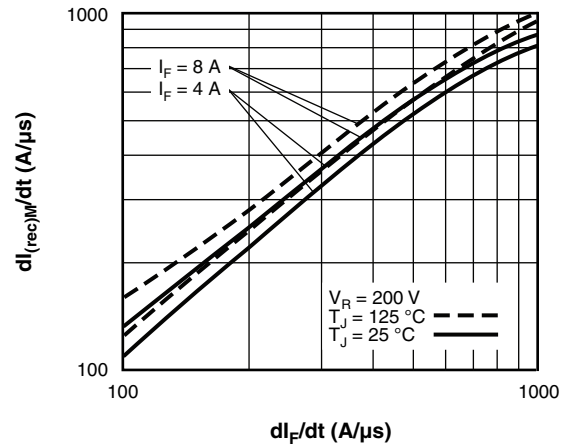


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics


Fig. 5 - Typical Reverse Recovery Time vs. dI_F/dt

Fig. 7 - Typical Stored Charge vs. dI_F/dt

Fig. 6 - Typical Recovery Current vs. dI_F/dt

Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt

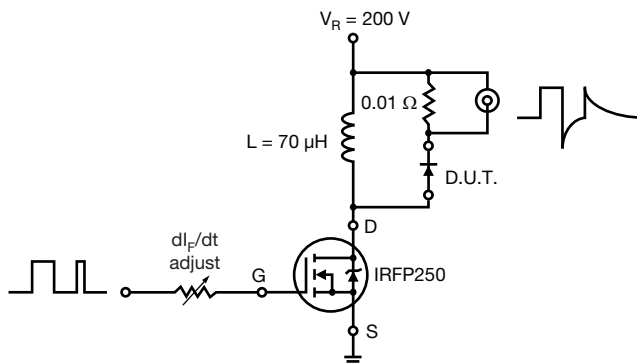


Fig. 9 - Reverse Recovery Parameter Test Circuit

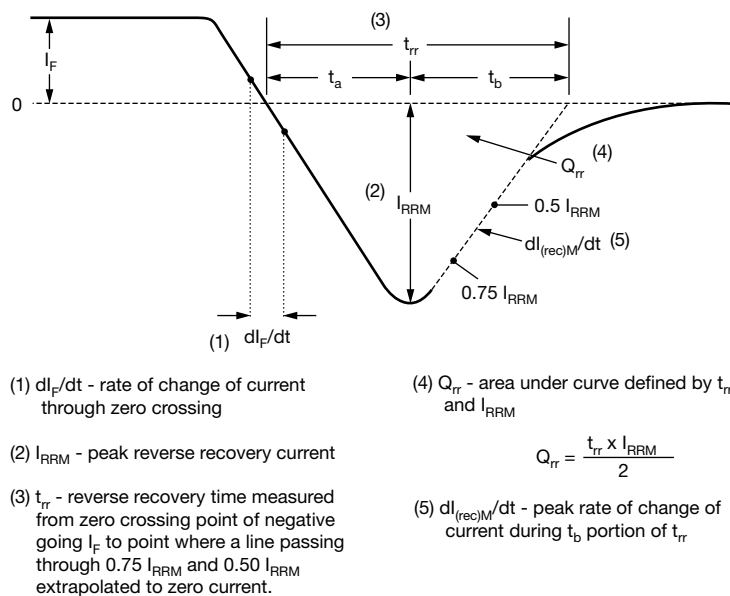


Fig. 10 - Reverse Recovery Waveform and Definitions

**ORDERING INFORMATION TABLE**

Device code	VS-	HF	A	04	SD	60	S	TR	H	M3
	1	2	3	4	5	6	7	8	9	10

- 1** - Vishay Semiconductors product
- 2** - HEXFRED® family
- 3** - Electron irradiated
- 4** - Current rating (04 = 4 A)
- 5** - D-PAK
- 6** - Voltage rating (60 = 600 V)
- 7** - S = D-PAK
- 8** -
 - TR = tape and reel
 - R = tape and reel (right oriented)
 - L = tape and reel (left oriented)
- 9** - H = AEC-Q101 qualified
- 10** - Environmental digit:
M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)

PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-HFA04SD60SHM3	75	3000	Antistatic plastic tube
VS-HFA04SD60STRHM3	2000	2000	13" diameter reel
VS-HFA04SD60STRRHM3	3000	3000	13" diameter reel
VS-HFA04SD60STRLHM3	3000	3000	13" diameter reel

LINKS TO RELATED DOCUMENTS

Dimensions	www.vishay.com/doc?95519
Part marking information	www.vishay.com/doc?95518
Packaging information	www.vishay.com/doc?95033



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